

consist of multiple, particularly symmetrically distributed heating elements, particularly such that can be actuated individually are also conceivable. One document that describes such an apparatus is WO2012083978A. The disadvantage in this case is that actuation of this nature also entails a correspondingly complicated control system.

Embodiments of the present invention provide an apparatus and a method which at least partially, and in particular completely eliminate the described drawbacks of the related art. In particular, Embodiments of the present invention provide an apparatus and a method with which it is possible to produce a desired temperature distribution on a surface, in particular a substrate surface.

The temperature distribution is preferably homogeneous, but in principle may be modulated in any way necessary. Additionally, an apparatus and method as per embodiments of the present invention are to be described with the aid of which it is possible to compensate for and/or offset an undesirable deformation of the heater.

According to a first aspect of the present invention, there is provided an apparatus for heating a substrate, comprising: a heater, a substrate holder with a substrate holder surface, wherein the substrate to be heated can be placed on the substrate holder surface, wherein the apparatus further comprises: means for exerting forces on the heater, a control unit for controlling the means, wherein the heater can be deformed by the means.

According to a second aspect of the present invention, there is provided a method for heating a substrate, in particular for creating a predetermined target temperature distribution in a substrate and/or to offset a deformation of the heater caused by external forces, preferably with the above apparatus, wherein a heater heats the substrate and a substrate holder holds the substrate in place on a substrate holder surface, wherein means exert forces on the heater, and wherein the means are controlled by a control unit, and wherein the heater is deformed by the means.

According to a third aspect of the present invention, there is provided an apparatus for processing and/or bonding a substrate, comprising the above apparatus.

According to a fourth aspect of the present invention, there is provided a method for processing and/or bonding a substrate, in particular with the above apparatus, wherein the substrate is heated with the above method.

The scope of of the invention also encompasses all combinations of at least two of the features presented in the description, the claims and/or the drawings. Where value ranges are specified, values within the stated limits are also to be considered disclosed as limit values and claimable in any combination.

In the following text, the terms substrate and substrate stack are used synonymously. In particular, a substrate may also consist of a plurality of substrates that are also arranged preferaly side by side on a substrate holder for processing.